



W25N01JW

- Higher density
- 83MB/s and up to 166MB/s

High Performance QspiNAND Flash

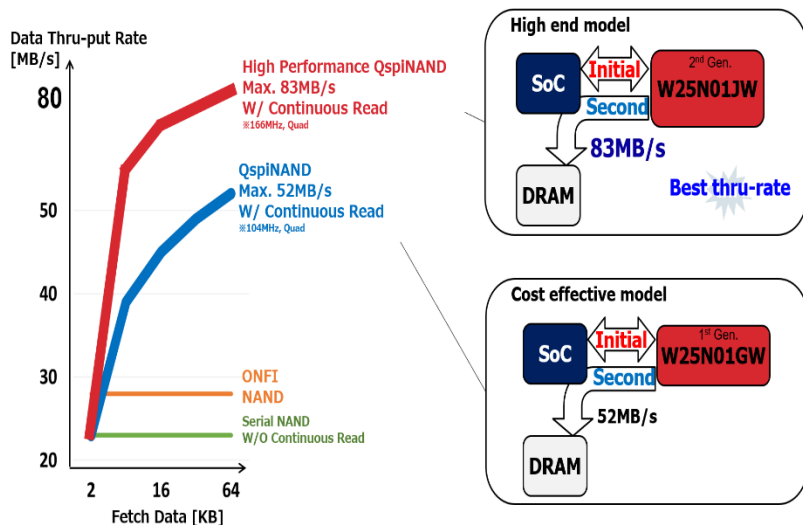
A better high-density storage option for sophisticated automotive display applications

General Description

The new W25N is a single-level cell (SLC) serial NAND Flash IC built using Winbond's proprietary 46nm fabrication process. SLC NAND has higher reliability than the higher-density multi-level cell (MLC) and triple-level cell (TLC).

Winbond new High Performance QspiNAND Flash enables a data transfer rate four times faster than Parallel NAND and other Serial NAND currently on the market.

Transferring data at 83MB/s, which far exceeds competing NAND flash on the market, Winbond's new solution accelerates instrument cluster boot-up time.



It also supports dual-quad I/O interface to accommodate higher storage density or data transfer rate up to 166 MB/s. The selection allowing for single, dual and quad I/O means customers can enjoy more flexibility compared to what competitors can offer.

Furthermore, Winbond this new High Performance QspiNAND Flash supports hardware reset pin which is more convenient for hardware / software design for automotive applications.

Automotive Applications

- Advanced Driver Assistance Systems (ADAS)
- Instrument Cluster Applications
- Center Information Display (CID)
- Vehicle-To-Everything (V2X)
- Fast Booting

Package Information

Voltage	Density	Part Number	Speed (MHz)	I/O	Package
1.8V	2Gb	W25N02JW	166 MHz (STR) 83 MHz (DTR)	x4	WSON 6x8 BGA24
	1Gb	W25N01JW	166 MHz (STR) 83 MHz (DTR)	x4	WSON 6x8 BGA24

* See data sheet for further technical information. This is subject to change without notice.

Own Logic and Memory Technology

Winbond Electronics Corp. is an Integrated IC Company engaged in IC design, manufacturing and sales services. From product design, research and development, wafer fabrication to marketing of brand name product, Winbond endeavors to provide its global clientele top quality of low to medium density memory solutions.

Own 12-inch Fab

Winbond specializes in the design of high-performance, low-power memory, and riding on the strength of having a 12-inch fab, offers a whole series of SLC code storage NAND flash memory and Mobile DRAM. The in house wafer fabrication provides customers with full commitment in capacity support as well as delivery flexibility.



winbond

Corporate Headquarter
No. 8, Keya 1^{st.}, Daya Dist., Taichung City 428, Taiwan
Tel: 886-4-25218168
Email: mkt_online@winbond.com

Winbond Electronics Corporation America
2727 North First Street, San Jose, CA 95134, U.S.A.
Tel : 1-408-943-6666



www.winbond.com